SLOVENSKI STANDARD

SIST EN 60749-25:2004

julij 2004

Semiconductor devices - Mechanical and climatic test methods - Part 25: Temperature cycling (IEC 60749-25:2003)

ICS 31.080.01

Referenčna številka
SIST EN 60749-25:2004(en)

EUROPEAN STANDARD **EN 60749-25**

NORME EUROPÉENNE

EUROPÄISCHE NORM September 2003

ICS 31.080.01

English version

Semiconductor devices - Mechanical and climatic test methods Part 25: Temperature cycling

(IEC 60749-25:2003)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques Partie 25: Cycles de température (CEI 60749-25:2003)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren Teil 25: Zyklische Temperaturwechsel (IEC 60749-25:2003)

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CENELEC
European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Ref. No. EN 60749-25:2003 E

Foreword

The text of document 47/1696/FDIS, future edition 1 of IEC 60749-25, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-25 on 2003-09-01.

This mechanical and climatic test method, as it relates to change of temperature, is a complete rewrite of the test contained in Subclause 1.1 of Chapter 3 of EN 60749:1999.

The following dates were fixed:

– latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2004-06-01
– latest date by which the national standards conflicting with the EN have to be withdrawn	(dow)	2006-09-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-25:2003 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

Publication	Year	Title	EN/HD	Year
IEC 60068-2-14	1984	Environmental testing Part 2: Tests - Test N: Change of temperature	EN 60068-2-14 [1)]	1999

[1)] EN 60068-2-14 includes A1:1986 to IEC 60068-2-14.

NORME INTERNATIONALE

INTERNATIONAL STANDARD

CEI
IEC
60749-25

Première édition
First edition
2003-07

Dispositifs à semiconducteurs –
Méthodes d'essais mécaniques et climatiques –

Partie 25:
Cycles de température

Semiconductor devices –
Mechanical and climatic test methods –

Part 25:
Temperature cycling

International Electrotechnical Commission, 3, rue de Varembé, PO Box 131, CH-1211 Geneva 20, Switzerland
Telephone: +41 22 919 02 11 Telefax: +41 22 919 03 00 E-mail: inmail@iec.ch Web: www.iec.ch

Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

CODE PRIX
PRICE CODE M

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SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 25: Temperature cycling

FOREWORD

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International Standard IEC 60749-25 has been prepared by IEC technical committee 47: Semiconductor devices.

This standard cancels and replaces IEC/PAS 62178 published in 2000. This first edition constitutes a technical revision.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1696/FDIS	47/1706/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.